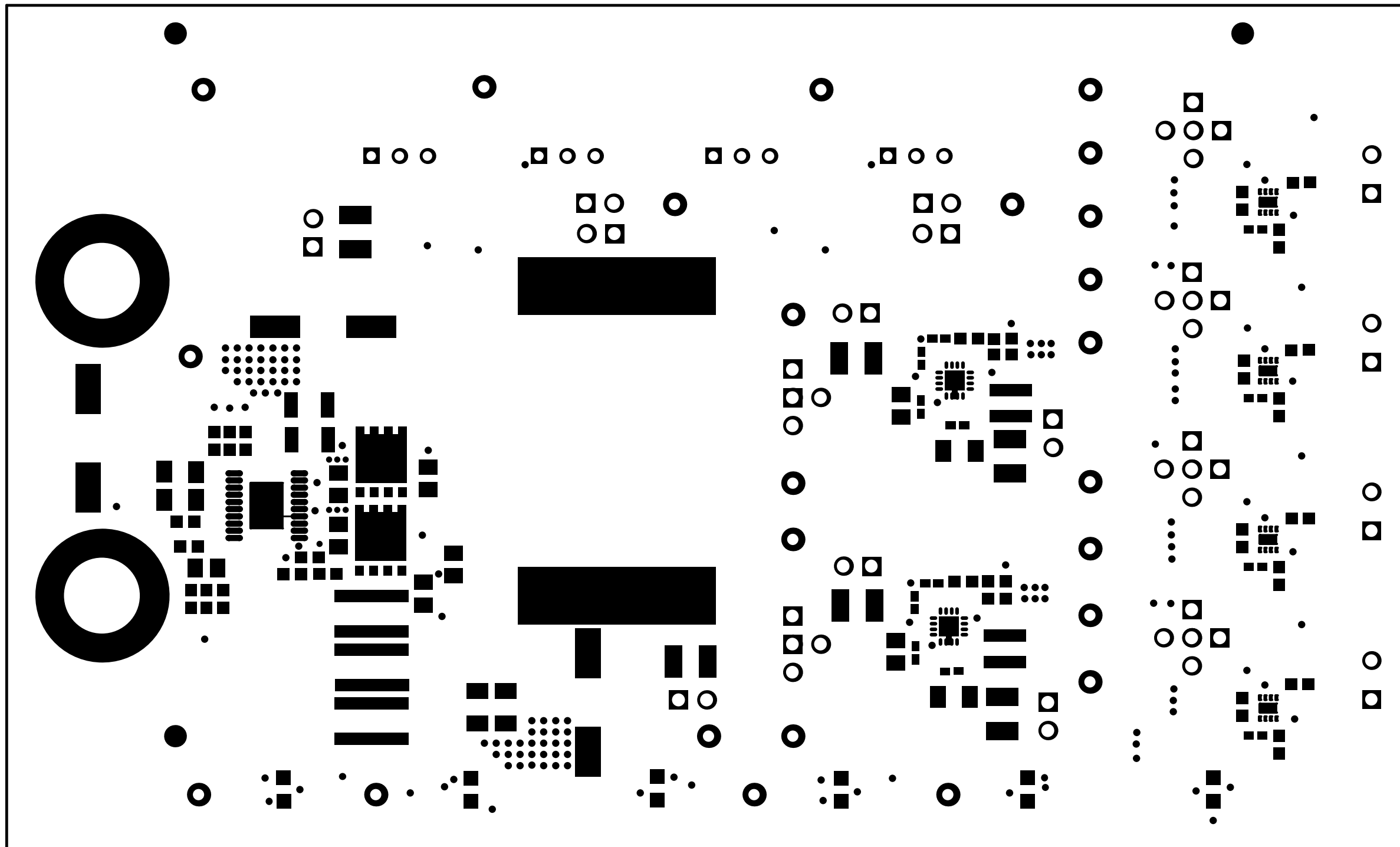
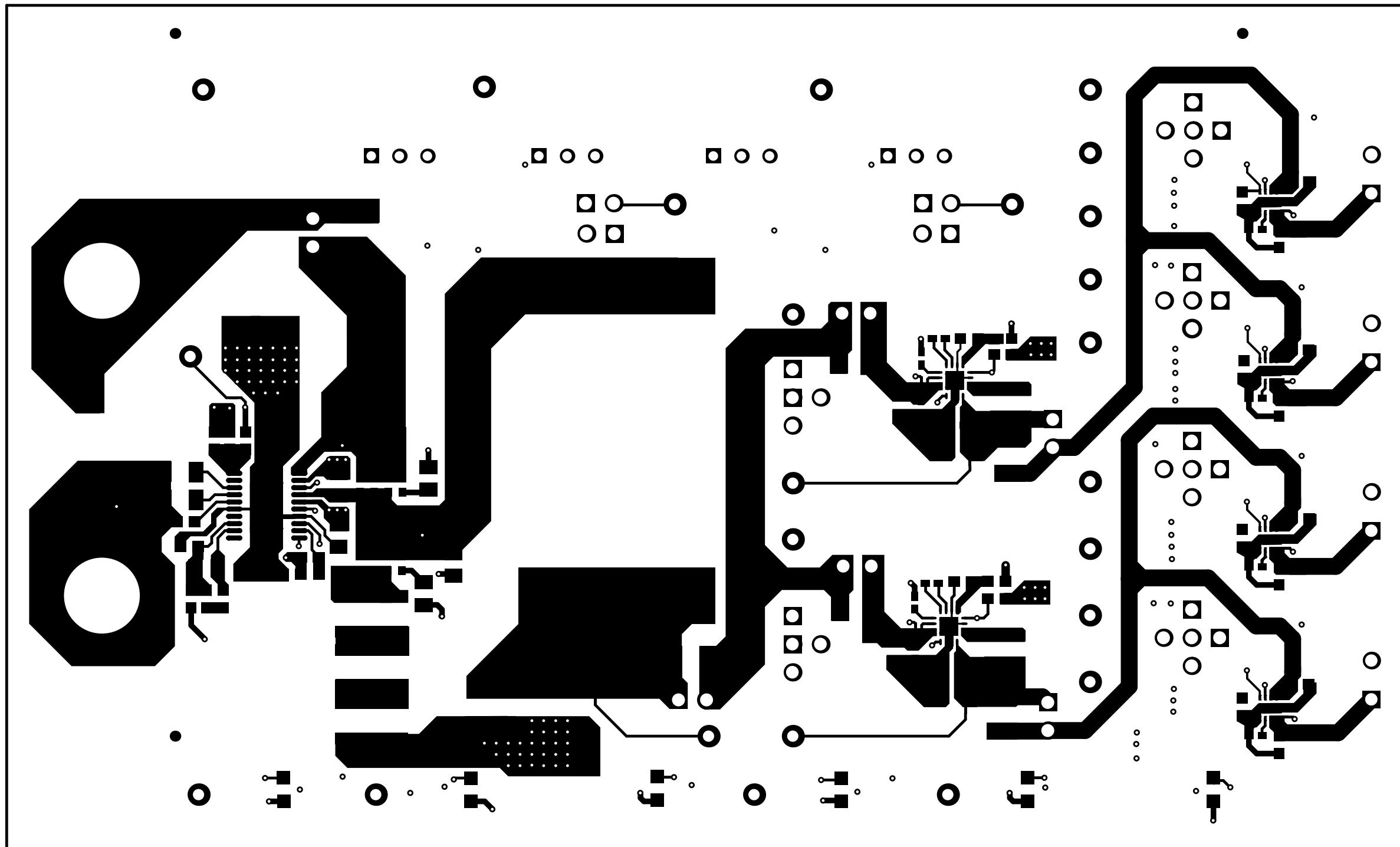


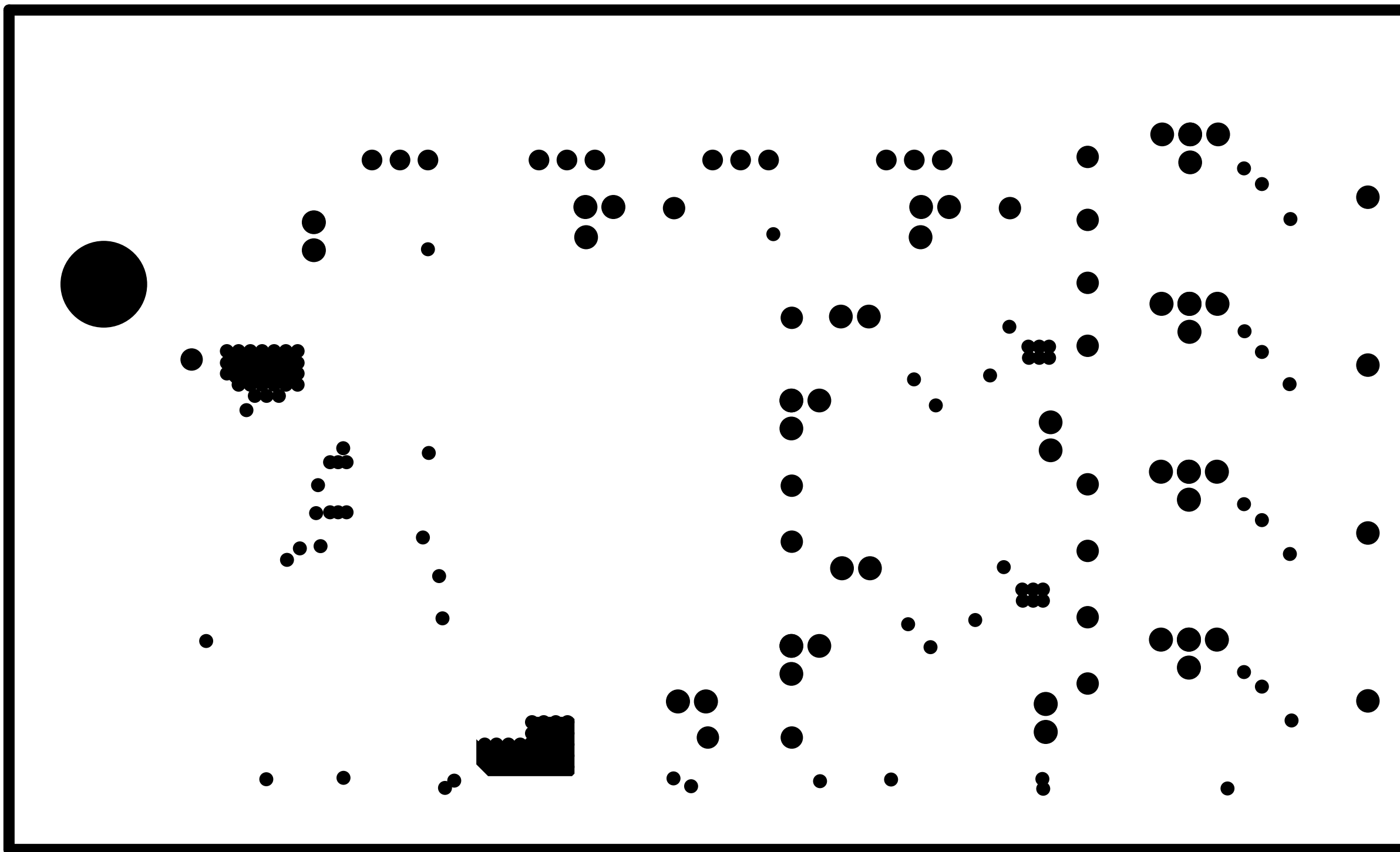
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00675		
PLOT NAME = Top Overlay	GENERATED : 11/11/2015	10:09:41 AM	TEXAS INSTRUMENTS



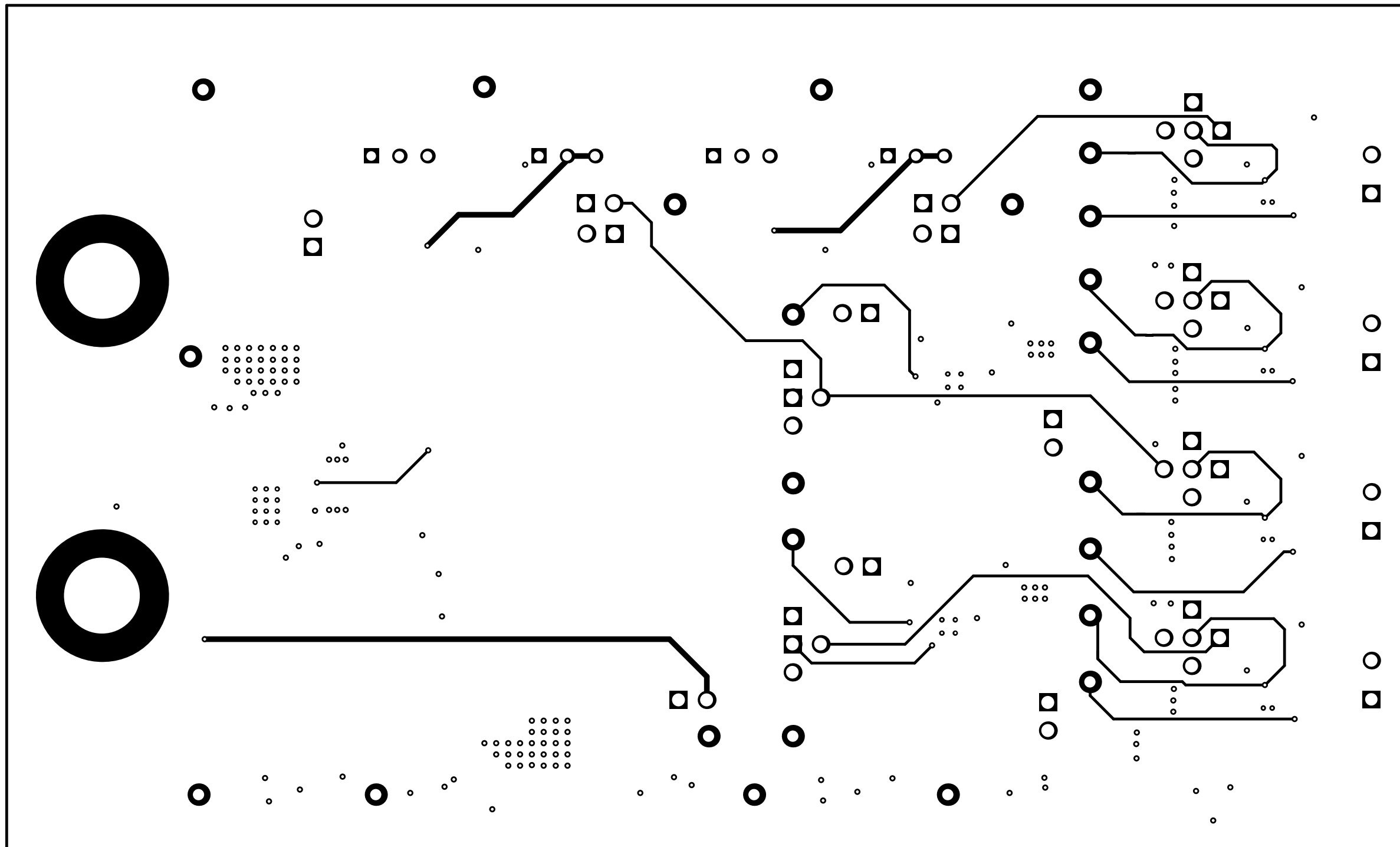
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00675		
PLOT NAME = Top Solder Mask	GENERATED : 11/11/2015 10:09:41 AM	TEXAS INSTRUMENTS	



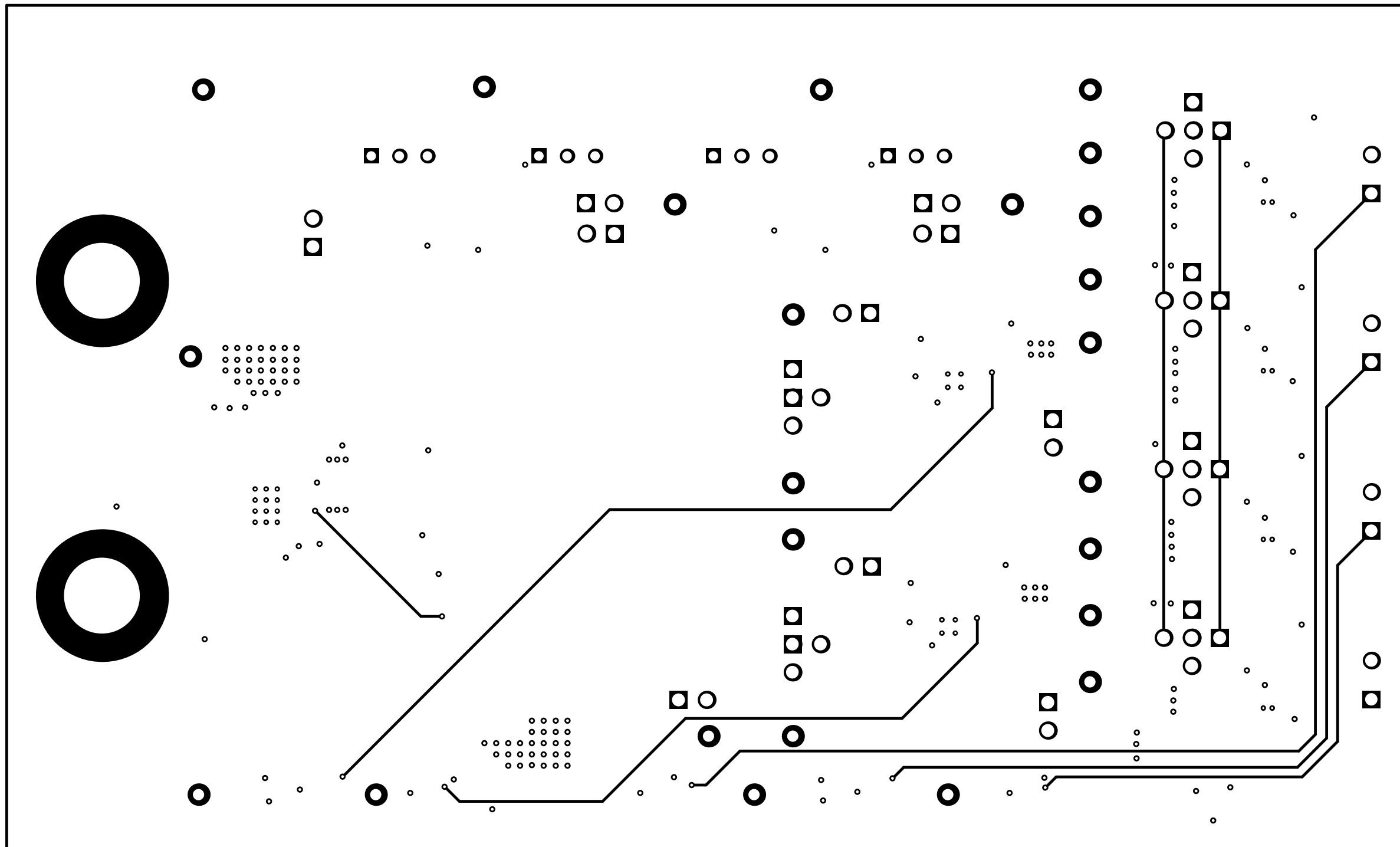
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00675		
PLOT NAME = Top Layer	GENERATED : 11/11/2015 10:09:42 AM	TEXAS INSTRUMENTS	



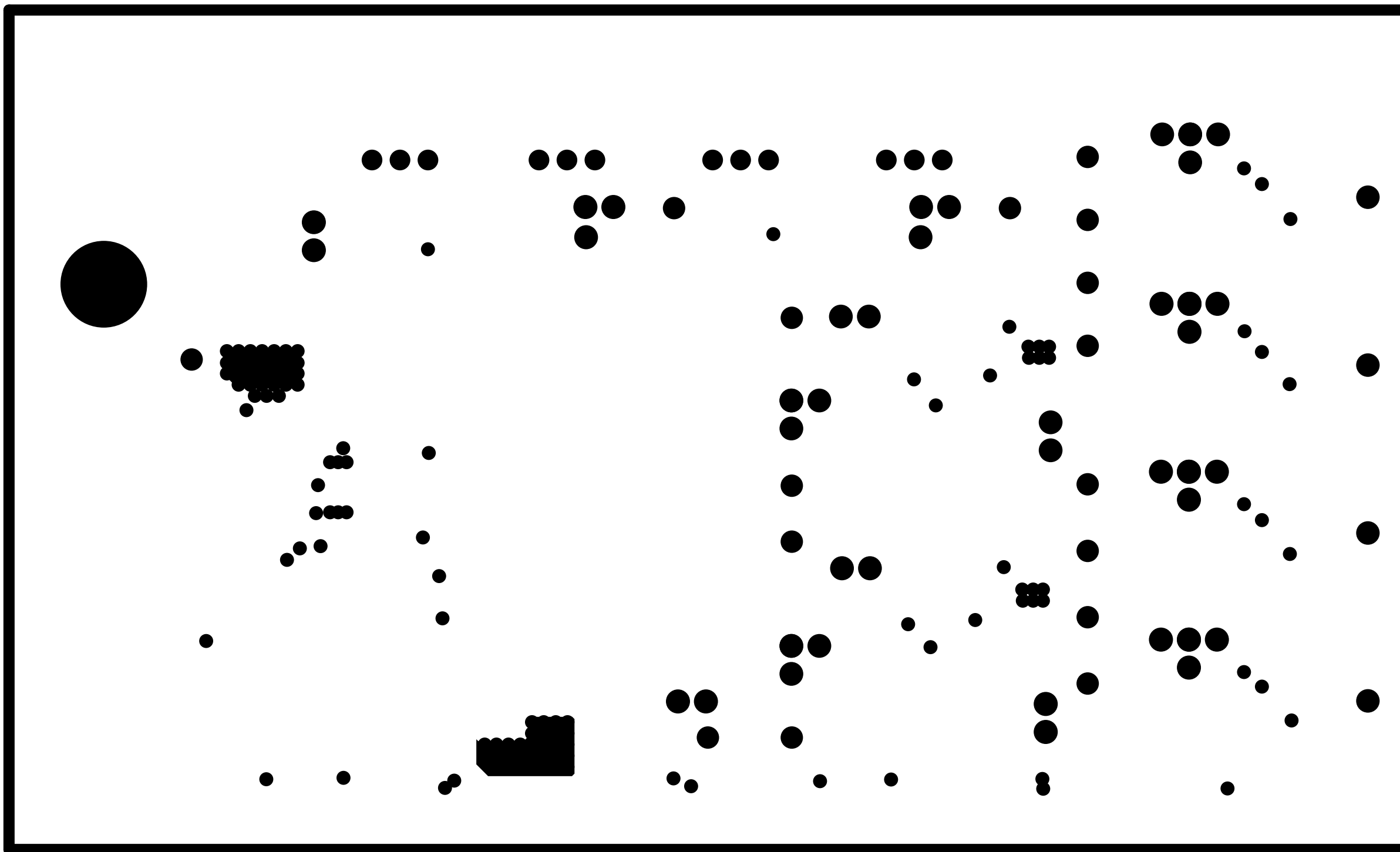
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00675		
PLOT NAME = Internal Plane 2	GENERATED : 11/11/2015 10:09:43 AM	TEXAS INSTRUMENTS	



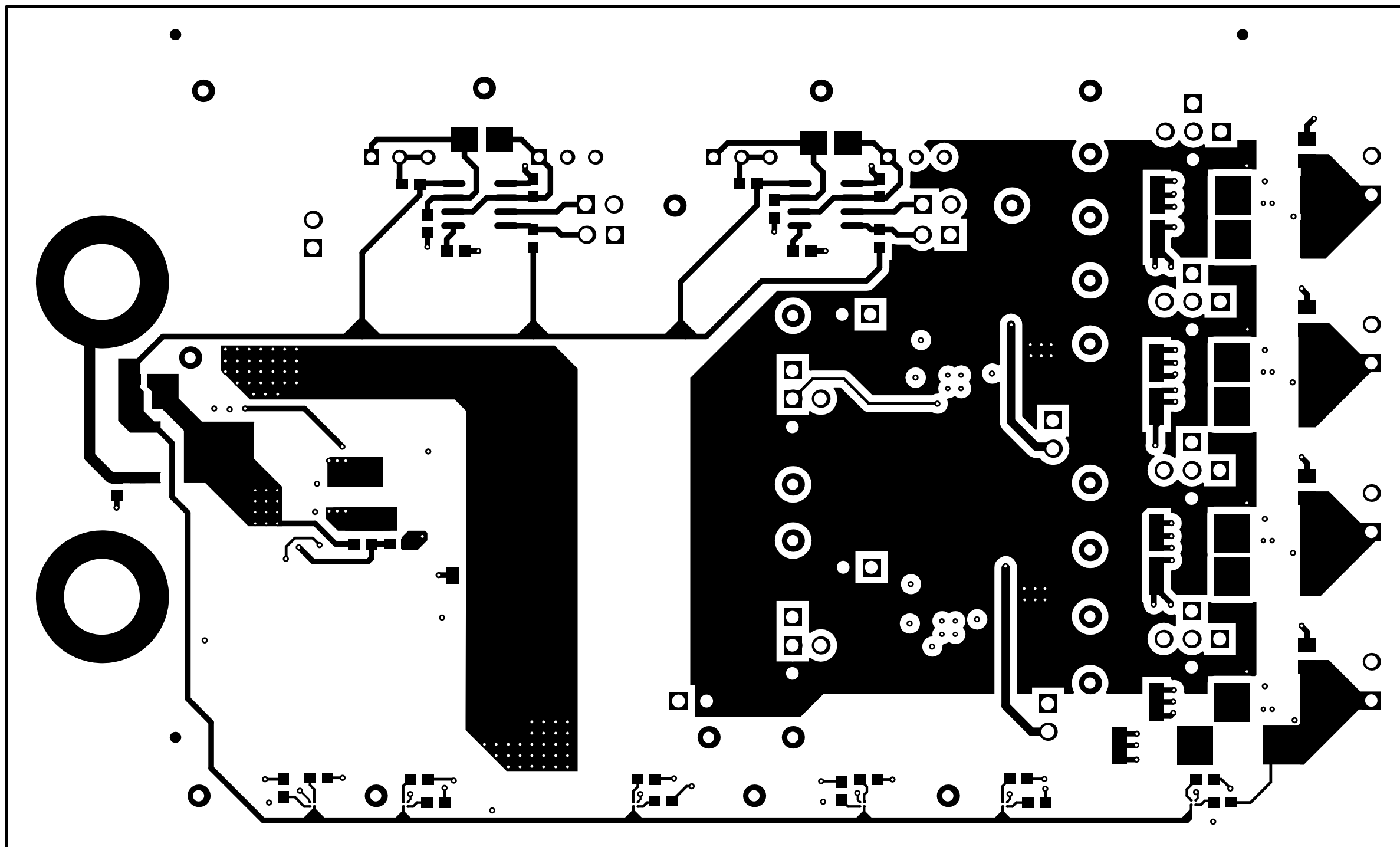
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00675		
PLOT NAME = Signal Layer 1	GENERATED : 11/11/2015 10:09:43 AM		TEXAS INSTRUMENTS



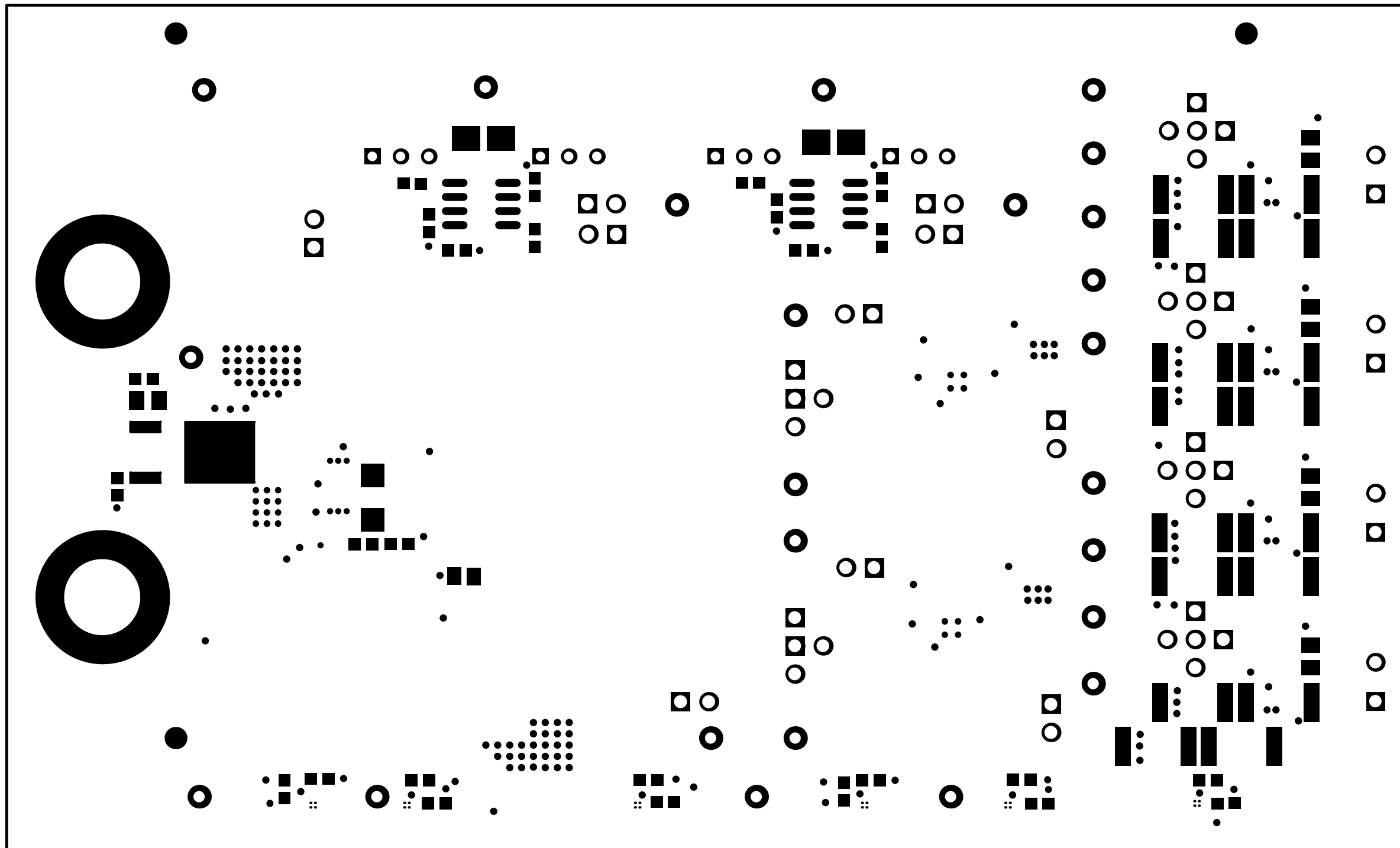
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00675		
PLOT NAME = Signal Layer 2	GENERATED : 11/11/2015	10:09:44 AM	TEXAS INSTRUMENTS



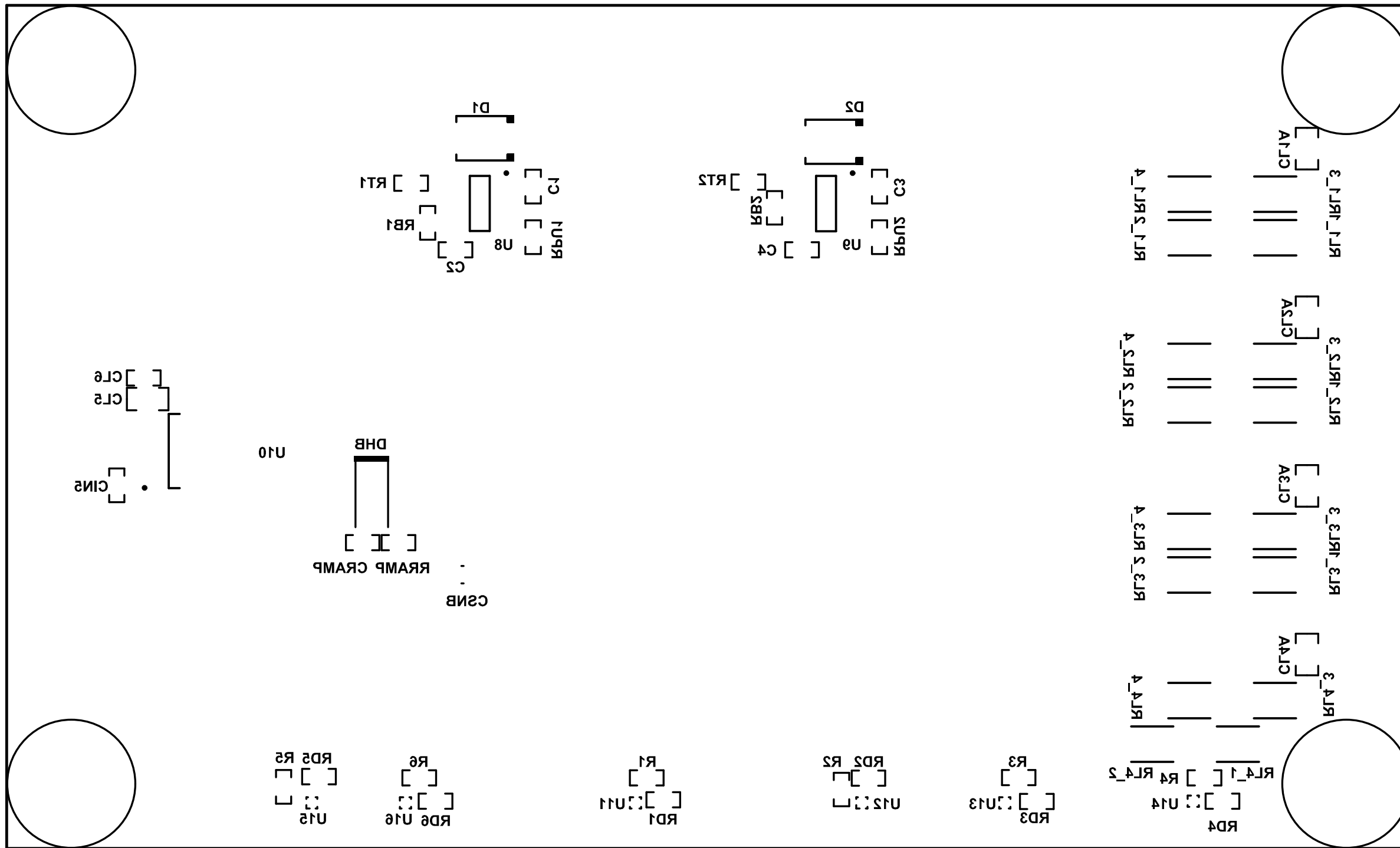
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00675		
PLOT NAME = Internal Plane 1	GENERATED : 11/11/2015 10:09:44 AM	TEXAS INSTRUMENTS	



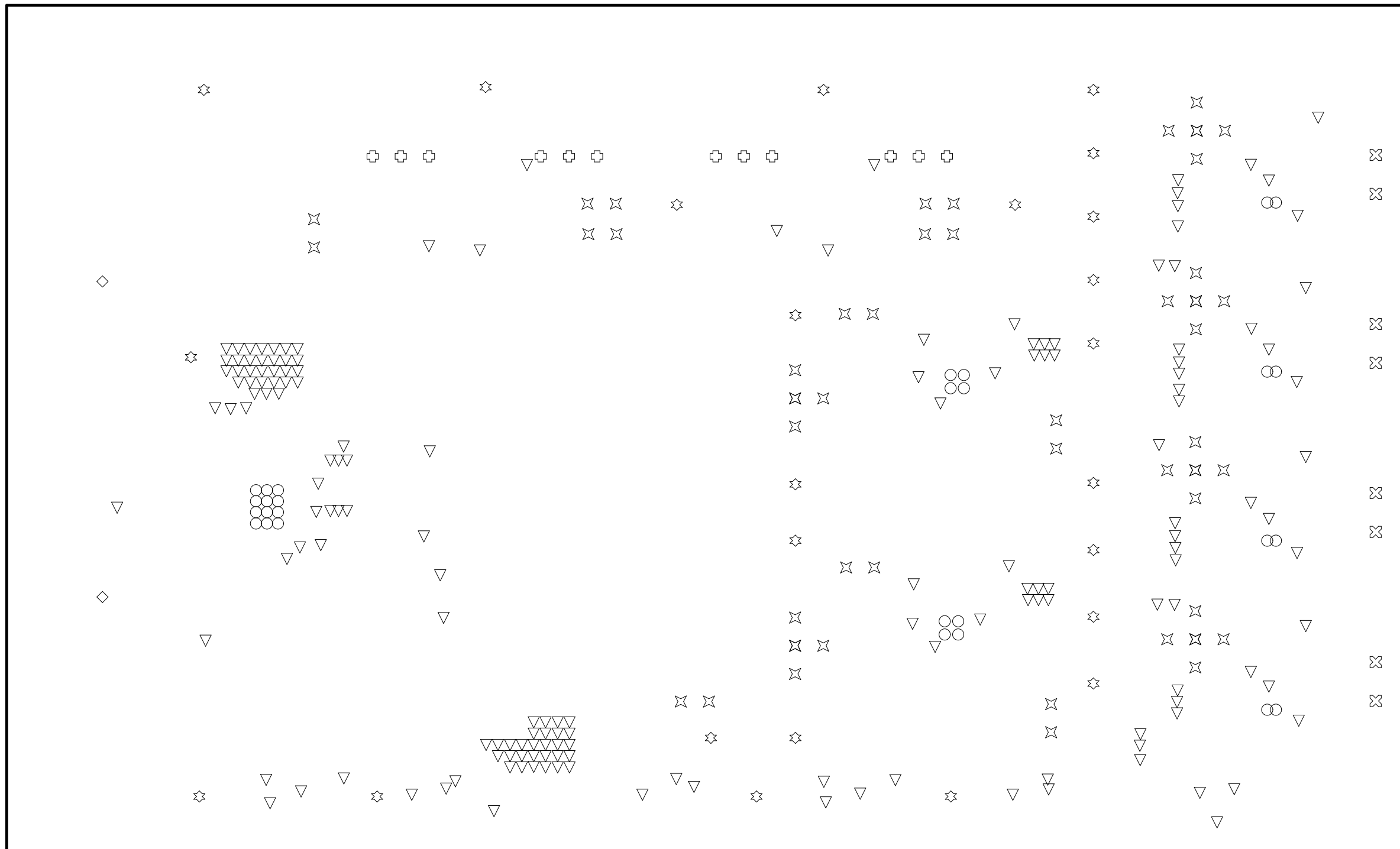
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00675		
PLOT NAME = Bottom Layer	GENERATED : 11/11/2015 10:09:45 AM	TEXAS INSTRUMENTS	



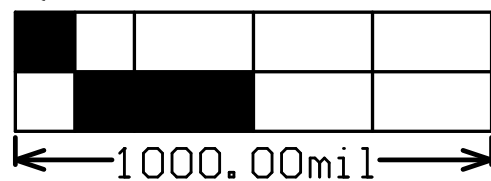
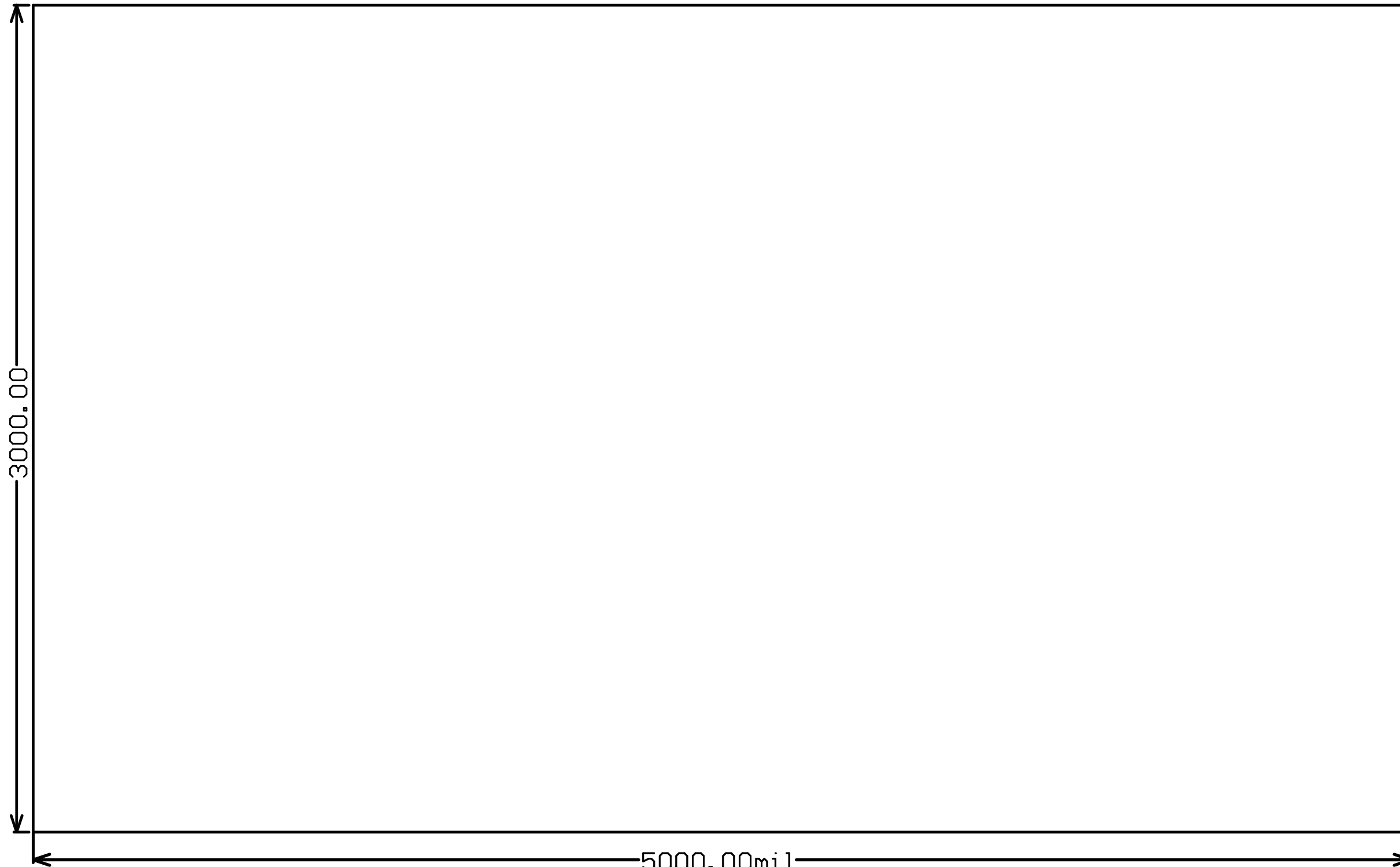
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00675		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/11/2015 10:09:45 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00675		
PLOT NAME = Bottom Overlay	GENERATED : 11/11/2015 10:09:46 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00675		
PLOT NAME = Drill Drawing	GENERATED : 11/11/2015	10:09:47 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00675	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00675		
PLOT NAME = Board Dimensions	GENERATED : 11/11/2015	10:09:47 AM	TEXAS INSTRUMENTS

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